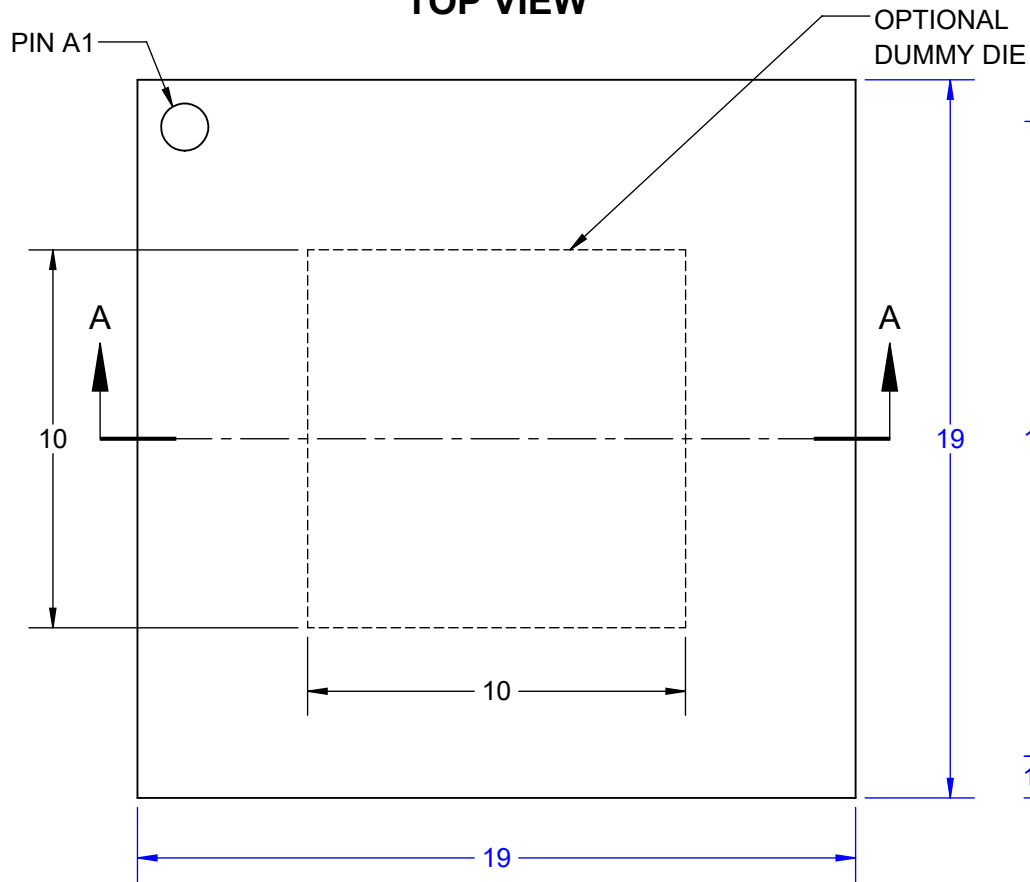
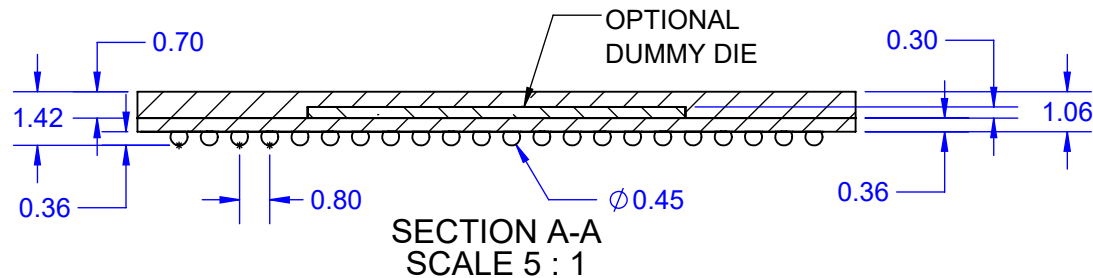
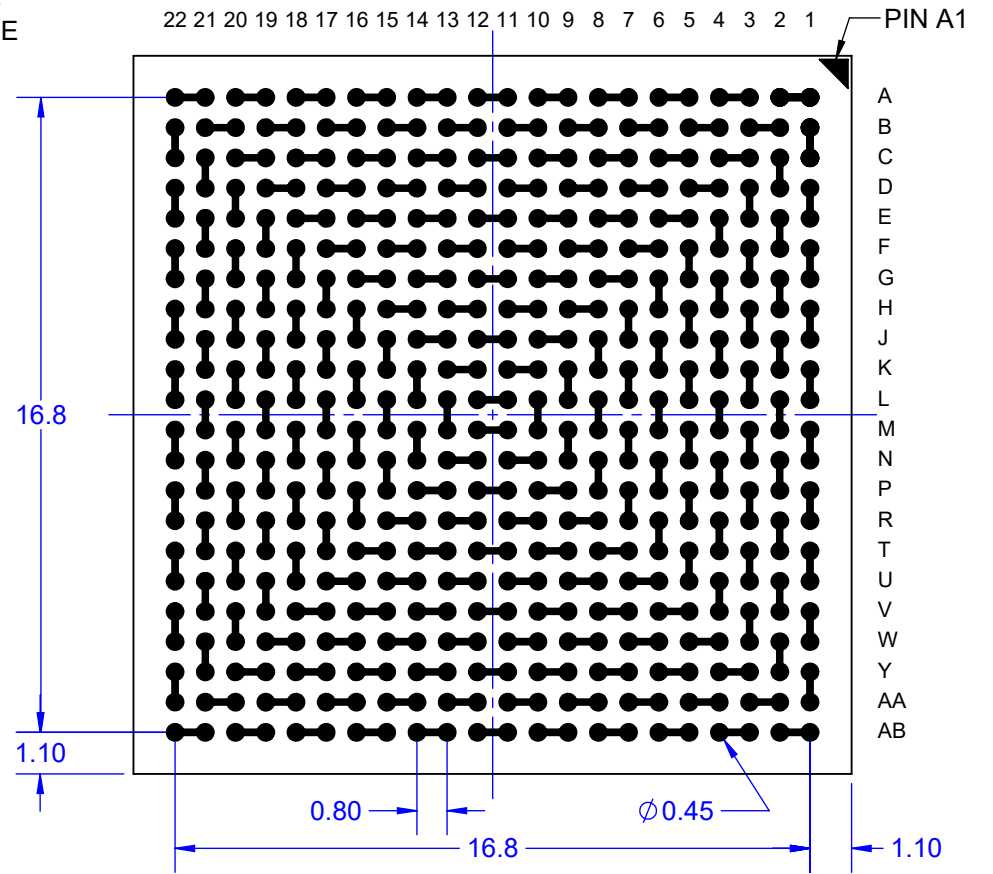


TOP VIEW



BALL VIEW



SECTION A-A
SCALE 5 : 1

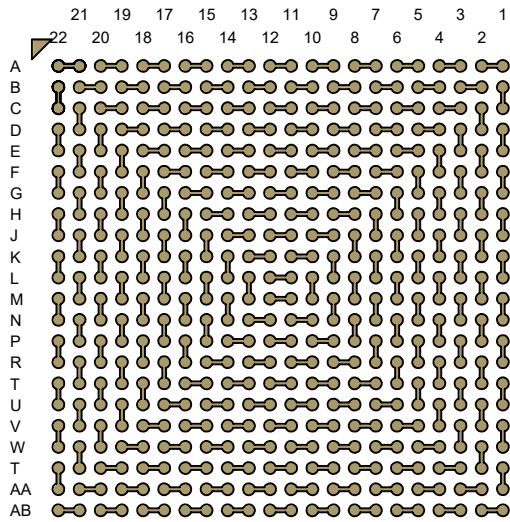
Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.45mm.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.40mm.
- 5) PAD Cu DIAMETER: 0.50mm.
- 6) SUBSTRATE MATERIAL: BT.
- 7) DUMMY DIE IS OPTIONAL.
- 8) MSL-3 RECOMMENDED BAKING 24 HOURS @125 °C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

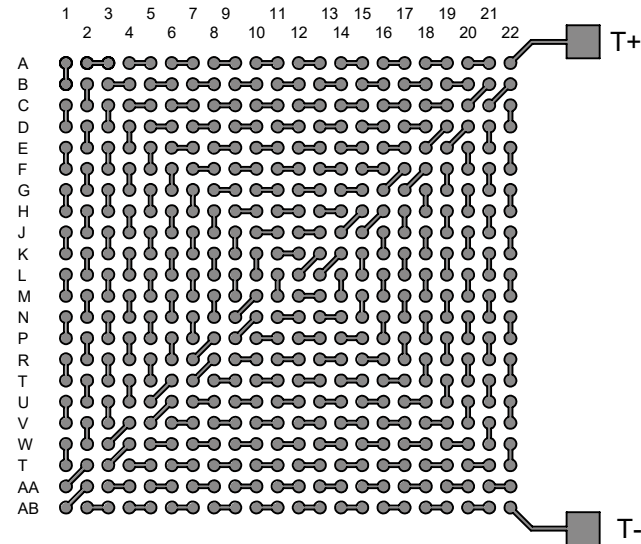
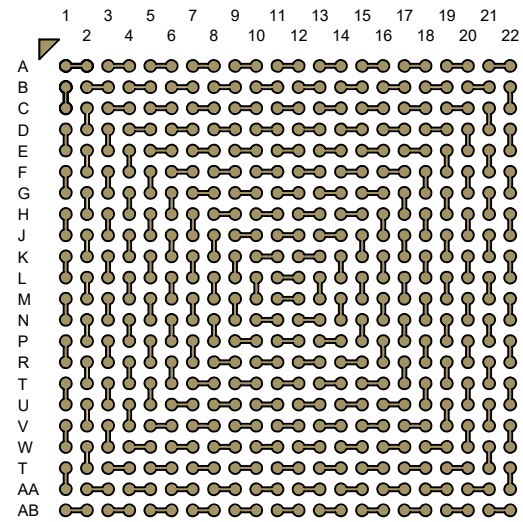
PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-Free	RoHS	Si DIE
BGA484T.8C-DC229D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
BGA484T.8-DC229D	Sn63/Pb37	NO	NO	YES

APPROVALS	DATE	TopLine [®]		
DRAWN T. Au	6/4/2022			
ENG M. Hart	6/4/2022	TITLE BGA484T.8C-DC229D DAISY CHAIN BGA		
MFG		SCALE 5:1	SIZE A	DRAWING NO. 582295
QA				REV A
CUST		DO NOT SCALE DRAWING		SHEET 1 OF 3
REVISED				

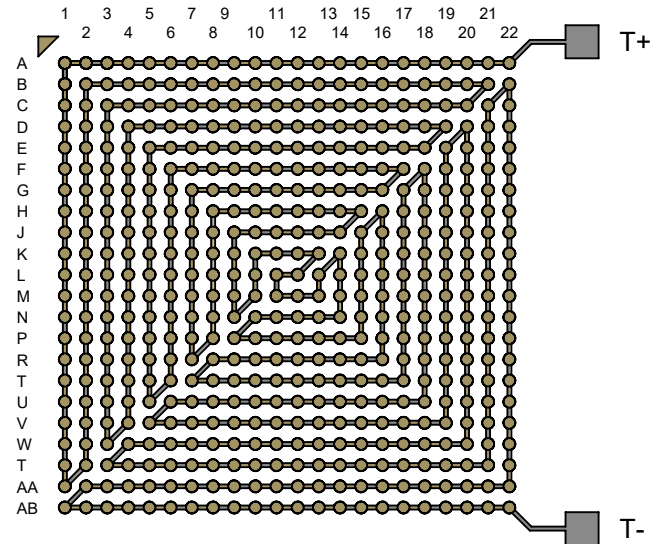
BALL VIEW



BOTTOM SIDE (TOP X-RAY VIEW)



TEST VEHICLE BOARD



AFTER MOUNTING

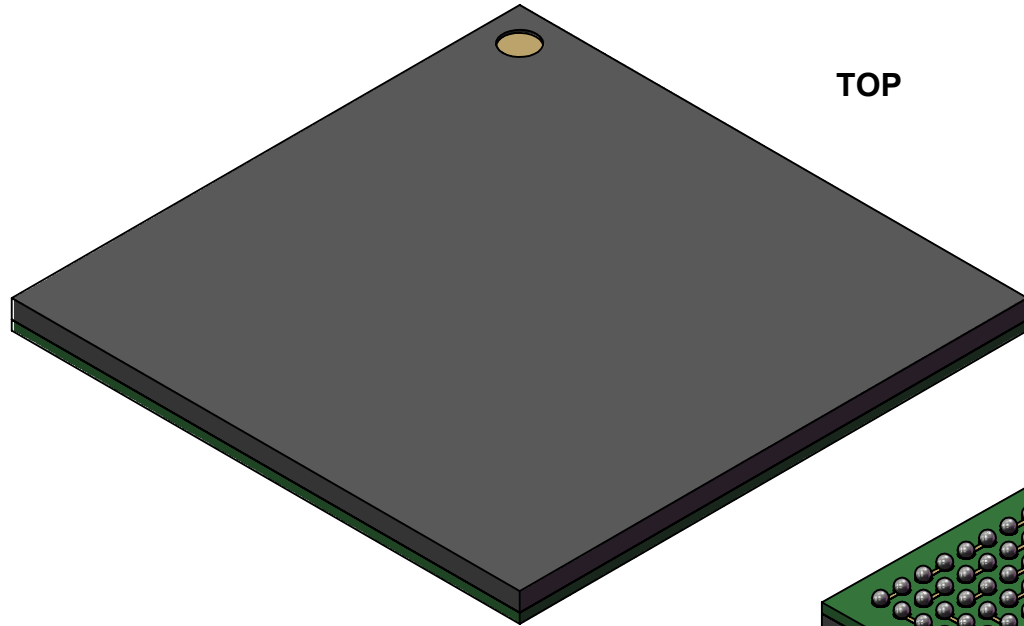
Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL DIAMETER 0.457mm (18 MIL).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.150mm (16 MIL).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.40mm (16MIL).

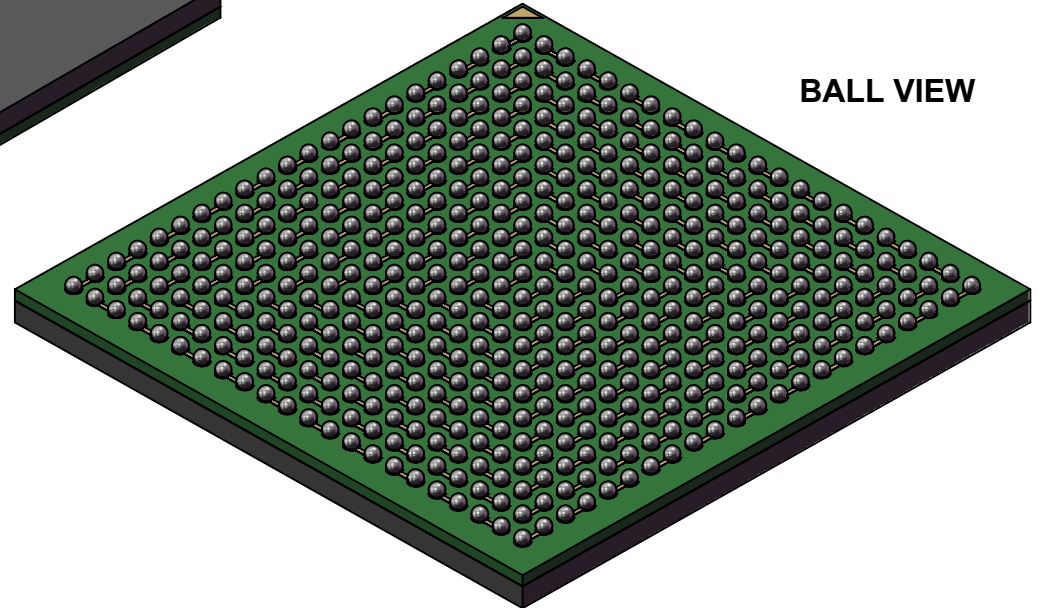
TopLine

TITLE			
BGA484T.8C-DC229D DAISY CHAIN BGA			
SCALE	SIZE	DRAWING NO.	REV
3.5:1	A	582295	A
DO NOT SCALE DRAWING			SHEET 2 OF 3

MODEL



TOP



BALL VIEW

TopLine[®]

TITLE BGA484T.8C-DC229D
DAISY CHAIN BGA

SCALE 5:1	SIZE A	DRAWING NO. 582295	REV A
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DO NOT SCALE DRAWING

SHEET 3 OF 3